Electronic Patent	App	lication Fee	Transm	ittal			
Application Number:	105	10585533					
Filing Date:	10-	10-Jul-2006					
Title of Invention:	Pol	Polyimide-Metal Laminated Body and Polyimide Circuit Board					
First Named Inventor/Applicant Name:	Tac	Tadahiro Yokozawa					
Filer:	The	Thomas Daniel Christenbury/Leslie Hood					
Attorney Docket Number:	SPL	SPL-06-1185					
Filed as Large Entity							
U.S. National Stage under 35 USC 371 Filing	Fee:	s					
Description		Fee Code	Quantity	Amount	Sub-Total ii USD(\$)		
Basic Filing:					1		
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Post-Allowance-and-Post-Issuance:  Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
	Total in USD (\$)			130